



**GP
ELECTRONICS**

**GPT016N10NTD
100V N-Channel MOSFET**

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
100V	1.6mΩ@10V	280A

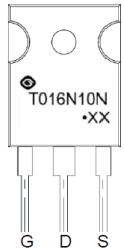
Feature

- Split Gate Trench Technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

- Power Switching Application

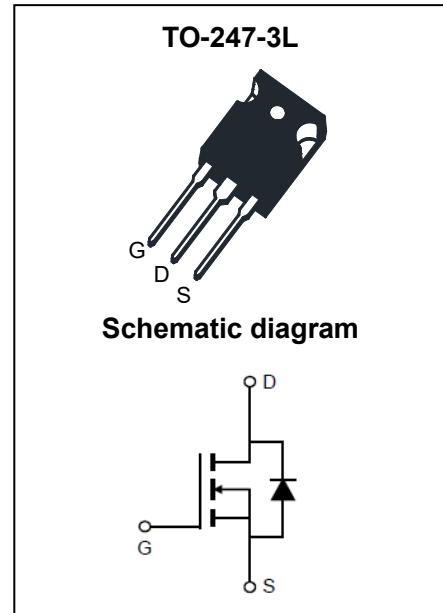
MARKING:



T016N10N = Device Code

XX = Date Code

Solid Dot = Green Indicator



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

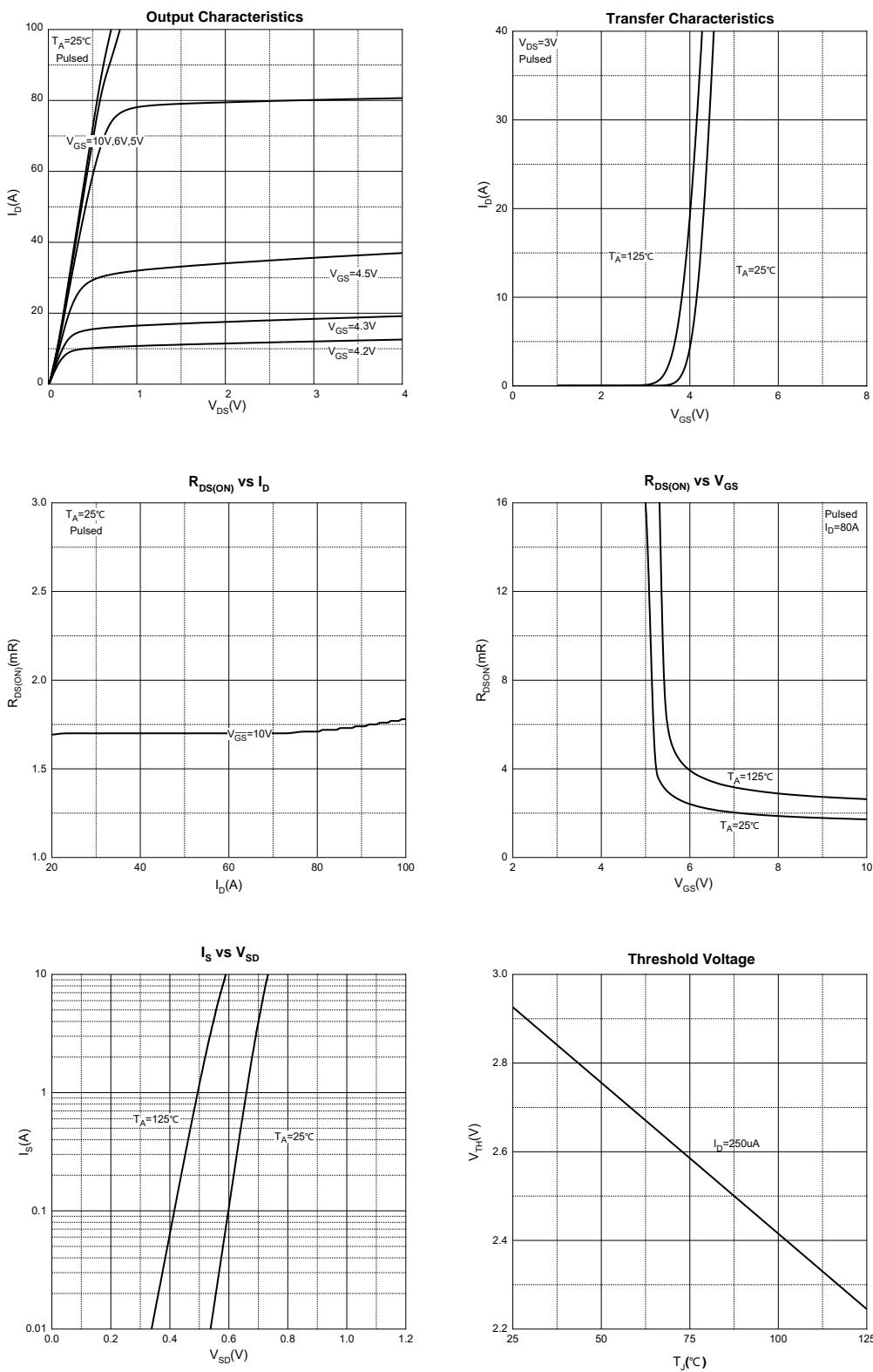
Parameter	Symbol	Value	Unit
Drain - Source Voltage	V_{DS}	100	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	I_D	280	A
	I_D	182	A
Pulsed Drain Current ²	I_{DM}	1120	A
Single Pulsed Avalanche Current ³	I_{AS}	90	A
Single Pulsed Avalanche Energy ³	E_{AS}	2300	mJ
Power Dissipation ⁵	P_D	347	W
Thermal Resistance from Junction to Ambient ⁶	$R_{\theta JA}$	40	$^\circ\text{C}/\text{W}$
Thermal Resistance from Junction to Case	$R_{\theta JC}$	0.36	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~+150	$^\circ\text{C}$

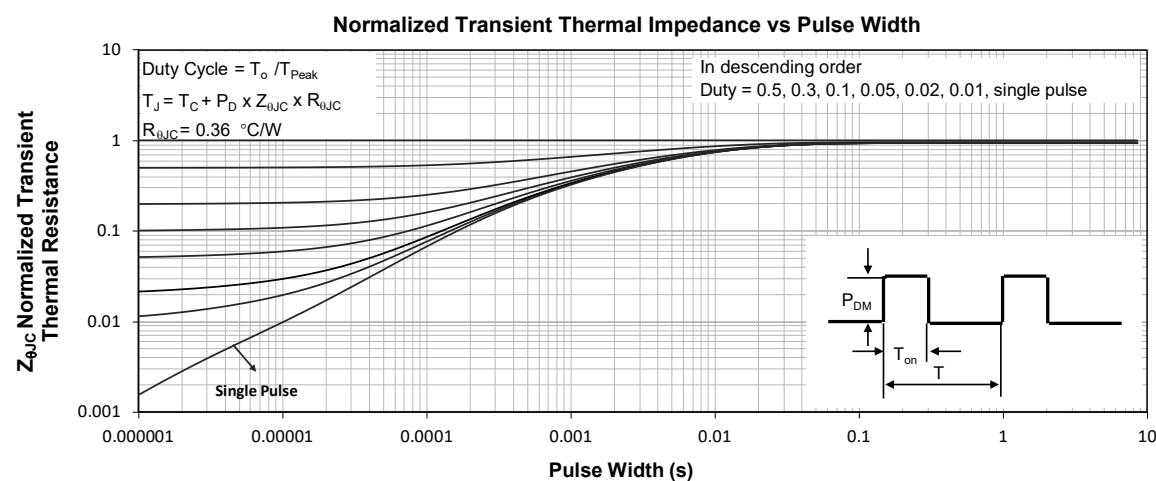
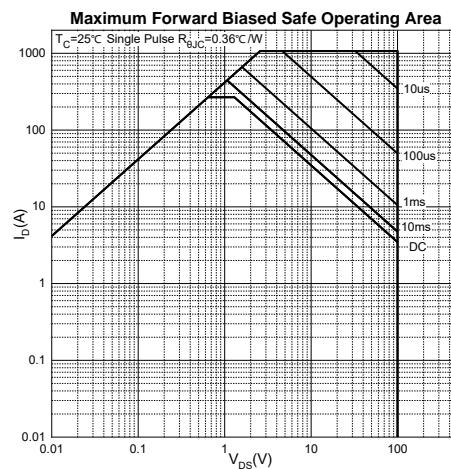
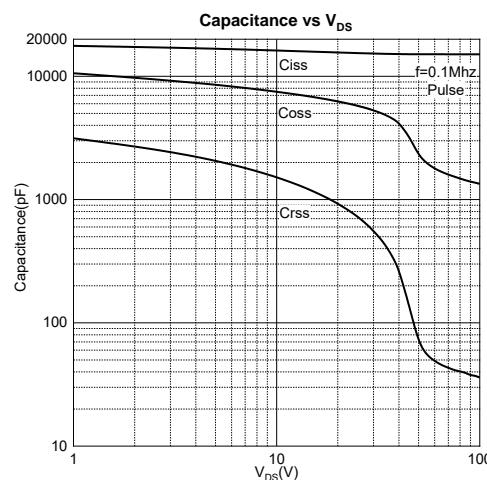
MOSFET ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

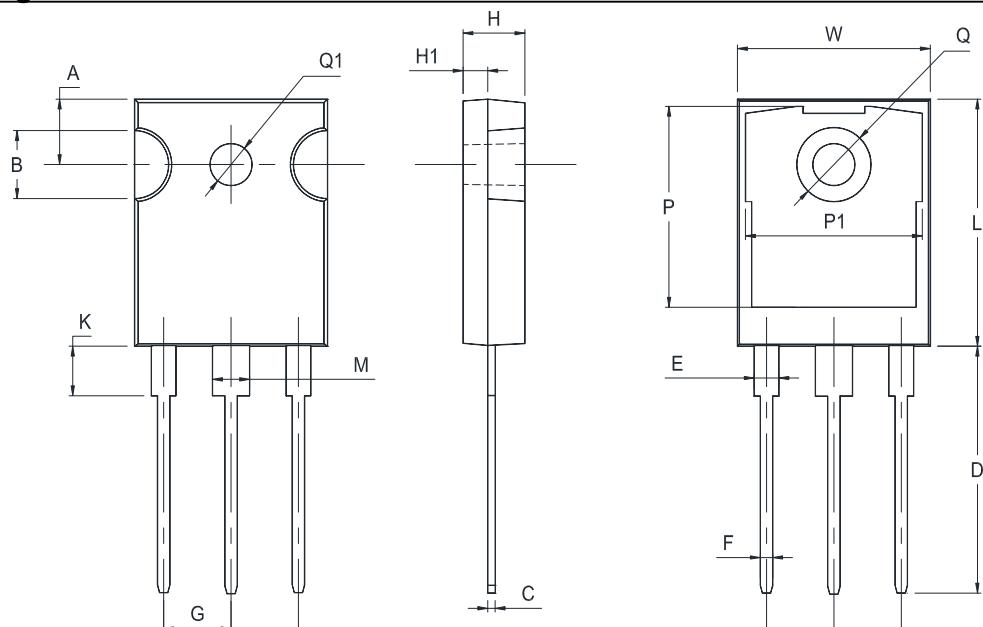
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 100\text{V}, V_{GS} = 0\text{V}$			1	μA
Gate - Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$			± 100	nA
On Characteristics⁴						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2	3	4	V
Drain-source On-resistance	$R_{DS(\text{on})}$	$V_{GS} = 10\text{V}, I_D = 20\text{A}$		1.6	2	$\text{m}\Omega$
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = 50\text{V}, V_{GS} = 0\text{V}, f = 0.1\text{MHz}$		15106		pF
Output Capacitance	C_{oss}			2280		
Reverse Transfer Capacitance	C_{rss}			69		
Gate Resistance	R_g	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		3		Ω
Switching Characteristics						
Total Gate Charge	Q_g	$V_{DS} = 50\text{V}, V_{GS} = 10\text{V}, I_D = 20\text{A}$		250.2		nC
Gate-source Charge	Q_{gs}			61.4		
Gate-drain Charge	Q_{gd}			68		
Turn-on Delay Time	$t_{d(\text{on})}$	$V_{DD} = 50\text{V}, I_D = 20\text{A}, R_G = 3\Omega$		40		ns
Turn-on Rise Time	t_r			90		
Turn-off Delay Time	$t_{d(\text{off})}$			160		
Turn-off Fall Time	t_f			100		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$V_{GS} = 0\text{V}, I_s = 10\text{A}$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu\text{s}$, duty cycle $\leq 1\%$.
- 3.E_{AS} condition: $V_{DD} = 50\text{V}, V_{GS} = 10\text{V}, L = 0.5\text{mH}, R_G = 25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- 4.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(\text{MAX})} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 6.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Characteristics




TO-247-3L Package Information


UNIT	A	B	C	D	E	F	G	W	H	H1	K	L	M	P
mm	6.5	5.2	0.7	20.3	2.2	1.3	5.7	16.2	5.3	2.5	4.45	21.3	3.2	16.6
mm	5.9	4.6	0.5	19.7	1.8	1.1	5.1	15.8	4.7	2.1	4.05	20.7	2.8	16.2

UNIT	P1	Q	Q1
mm	14.2	7.35	4.2
mm	13.8	7.05	3.6

